



## Features

- NXP Cortex™-A53, i.MX 8M Plus Quad 1.6 GHz processor
- 4GB DDR4, up to 64GB eMMC
- Video decode/encode, up to 1080p/60fps.
- Rich peripheral I/O support
- Low power, no heatsink required
- Wide-range operating temperature (-40°C~85°C)

## Specifications

Form Factor	SOM Module (System-on-Module)
Processor	NXP i.MX8M Plus Quad Cortex-A53 processor
System Memory	3GB LPDDR4 on board (optional 1GB, 2GB or 4GB)
Flash Memory	16GB eMMC on board (up to 64GB)
Display	HDMI 2.0 1x dual-channel LVDS 1x MIPI-DSI 4-lane
Video Codec	Up to 1080p decode, AVC/H.264, HEVC/H.265 Up to 1080p encode, AVC/H.264, HEVC/H.265
Graphics	Open VG 1.1, Open GL ES 3.1, Vulkan, Open CL 1.2 FP
Audio Interface	2x SAI
LAN	2x GbE GMAC
USB	2x USB 3.0
Image Capture Interface	2x MIPI-CSI (4 lanes)
Serial Interface	4x UART, 1x CSPI, 1x QSPI Interface
Media Interface	2x High-speed SDIO
PCI-E	1x PCI-E (Gen2)
SATA	N/A
GPIO	N/A
I <sup>2</sup> C	3x I <sup>2</sup> C
Others	N/A
CAN Bus	2x CAN FD
Dimensions	36mm x 49mm (1.4" x 1.9")
Environment	Humidity: 0 % to 90 % RH at 60° C (non-condensing) Shock: Non-Operating: 1G, 15 mins (x-, y-, z-axis) Vibration: Non-operating: 3 Hz to 500 Hz, 15 mins
Operating Temperature	-40°C~+85°C (-40°F ~ 185°F)
OS Support	Yocto 3.0 (sumo, kernel 5.4.70) Android 11
Certification	CE/ FCC Class-A

## Ordering Information

RM-H8MP-S	RISC System on Module, 3GB LPDDR4, 16GB eMMC
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## Dimensions

